Transmitted herewith for filing is the Patent Application of:

Inventor: EE HUA WONG, RANJAN S/O RAJOO, POI SIONG TEO

For: WAFER LEVEL SUPER STRETCH SOLDER

22390 U.S. PTO 10/748736

Enclosed	l are:						
x	6 sheets of drawing(s) - formal.						
	An assignment of the invention to Agency For Science, Tachnology and Research, Notional University of Sign An assignment of the invention to Agency For Science, Tachnology and Research Corporation						
	An associate power of attorney Applicant claims small entity status						
	Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filin	g fee has been	calculated as shown bel	ow:				
		(Col. 1)	(Col. 2)	OTHER THAN A	A SMALL ENTITY		
FOR:		NO. FILED	NO. EXTRA	RATE	FEE		
BASIC FEE		> <	\rightarrow		\$ 770.		
	L CLAIMS	31 -20=	11	x 18 =	\$ 198.		
INDEP CLAIMS		7 -3=	4	x 86 =	\$ 344.		
			S	SUB TOTAL	\$ 1,312.	·	
				ASSIGNMENT	\$.		
				TOTAL	\$ 1.312.		
x	Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,312. A duplicate copy of this sheet is enclosed.						
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	X A	X Any additional filing fees required under 37 CFR §1.16.					
	X Any patent application processing fees under 37 CFR §1.17.						
	Respectfully submitted						

EXPRESS MAIL CERTIFICATE

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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